

ABSTRACT

The present invention relates to an adhesive and more particularly to a moisture curable adhesive. In one embodiment, the present invention includes a moisture curable adhesive comprising a polymer or copolymer including reactive silicon end groups; from about .01 to about 40 percent by weight of a clear filler that will not substantially interfere with the clarity of the adhesive; and from about 0.01 to about 10 percent by weight of a dehydrating agent. In another embodiment, the present invention includes a moisture curable adhesive comprising a copolymer including a reactive silicon group; from about 33 to about 85 percent by weight of a filler; and from about 0.01 to about 10 percent by weight of a dehydrating agent. The present invention is further directed to a method of joining two adherends.

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